

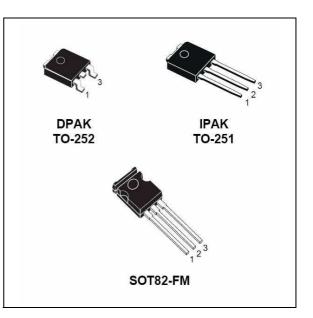
# VND7N04, VND7N04-1 VNK7N04FM

# "OMNIFET": Fully autoprotected power MOSFET

### Features

Туре	V <sub>clamp</sub>	R <sub>DS(on)</sub>	I <sub>lim</sub>
VND7N04	42 V	0.14 Ω	7 A
VND7N04-1	42 V	0.14 Ω	7 A
VNK7N04FM	42 V	0.14 Ω	7 A

- Linear current limitation
- Thermal shut down
- Short circuit protection
- Integrated clamp
- Low current drawn from input pin
- Diagnostic feedback through input pin
- ESD protection
- Direct access to the gate of the power MOSFET (analog driving)
- Compatible with standard power MOSFET



### Description

The VND7N04, VND7N04-1 and VNK7N04FM are monolithic devices made using STMicroeletronics VIPower M0 Technology, intended for replacement of standard power MOSFETS in DC to 50 KHz applications. Built-in thermal shut-down, linear current limitation and overvoltage clamp protect the chip in harsh enviroments.

Fault feedback can be detected by monitoring the voltage at the input pin.

Table 1. Device summary

Part number	Order code
VND7N04	VND7N04, VND7N04-1-E, VND7N04-E, VND7N0413TR, VND7N04TR-E
VND7N04-1	VND7N04-1
VNK7N04FM	VNK7N04FM

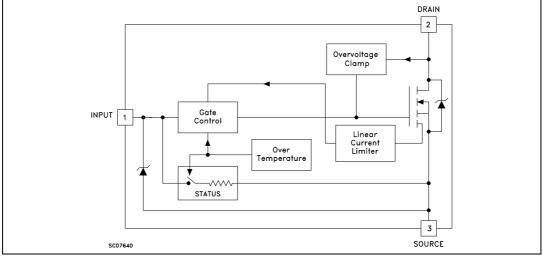
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# 1 Block diagram







## 2 Electrical specification

## 2.1 Absolute maximum rating

		Va	lue	
Symbol	Parameter	DPAK IPAK	SOT-82FM	Unit
Vds	Drain-source voltage (V <sub>in</sub> = 0)	Internally	clamped	V
Vin	Input voltage	1	8	V
lo	Drain current	Internall	y limited	А
lr	Reverse DC output current	-7		А
Vesd	Electrostatic discharge (C = 100 pF, R=1.5 K $\Omega$ )	2000		V
Ptot	Total dissipation at $T_c = 25 $ °C	60	9	W
Tj	Operating junction temperature	Internall	y limited	C
Τc	Case operating temperature	Internall	y limited	°C
Tstg	Storage temperature	-55 to	o 150	°C

## 2.2 Thermal data

Table 3. Thermal data

		DPAK/IPAK	SOT82-FM	
Rthj-case	Thermal resistance junction-case max	3.75	14	C/M
Rthj-amb	Thermal resistance junction-ambient max	100	100	°C/W

### 2.3 Electrical characteristics

### Table 4. Electrical characteristics: off

(-40 < Tj < 125  $^{\circ}$ C unless otherwise specified)

	· · · · · ·					
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>CLAMP</sub>	Drain-source clamp voltage	I <sub>D</sub> = 200 mA V <sub>in</sub> = 0	32	42	52	V
V <sub>CLTH</sub>	Drain-source clamp threshold voltage	$I_D = 2 \text{ mA } V_{in} = 0$	31			V
V <sub>INCL</sub>	Input-source reverse clamp voltage	I <sub>in</sub> = -1 mA	-1.1		-0.25	V
I <sub>DSS</sub>	Zero input voltage drain current (V <sub>in</sub> = 0)	$V_{DS} = 13 V V_{in} = 0$ $V_{DS} = 25 V V_{in} = 0$			75 200	μΑ μΑ
I <sub>ISS</sub>	Supply current from input pin	V <sub>DS</sub> = 0 V V <sub>in</sub> = 10 V		250	550	μA



Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>IN(th)</sub>	Input threshold voltage	$V_{DS} = V_{in} I_D + I_{in} = 1 mA$	0.8		3	V
	Static drain-source on resistance	V <sub>in</sub> = 10 V I <sub>D</sub> = 3.5 A			0.14	Ω
		V <sub>in</sub> = 10 V I <sub>D</sub> = 3.5 A V <sub>in</sub> = 5 V I <sub>D</sub> = 3.5 A			0.28	Ω
R-ac )		-40 < T <sub>j</sub> < 25 ℃				
R <sub>DS(on)</sub>		$V_{in} = 10 V I_{D} = 3.5 A$			0.28	Ω
		$V_{in} = 5 V I_D = 3.5 A$			0.56	Ω
		T <sub>j</sub> = 125 ℃				

#### Table 5. **Electrical characteristics: on**

#### Table 6. **Electrical characteristics: dynamic**

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
9 <sub>fs</sub> <sup>(1)</sup>	Forward transconductance	V <sub>DS</sub> = 13 V I <sub>D</sub> = 3.5 A	2	5		S
C <sub>oss</sub>	Output capacitance	$V_{DS} = 13 V f = 1 MHz V_{in} = 0$		250	500	pF

1. Pulsed: Pulse duration =  $300 \mu s$ , duty cycle 1.5 %

Table 7.	Electrical characteris	stics: switching	
Symbol	Parameter	Test conditions	
t <sub>d</sub> (on)	Turn-on delay time	$V_{DD} = 15 V I_d = 3.5 A$	

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>d</sub> (on)	Turn-on delay time	V <sub>DD</sub> = 15 V I <sub>d</sub> = 3.5 A		50	150	ns
t <sub>r</sub>	Rise time	$V_{gen} = 10 \text{ V R}_{gen} = 10 \Omega$		60	180	ns
t <sub>d</sub> (off)	Turn-off delay time	(see Figure 26)		130	300	ns
t <sub>f</sub>	Fall time			50	200	ns
t <sub>d</sub> (on)	Turn-on delay time	V <sub>DD</sub> = 15 V I <sub>d</sub> = 3.5 A		140	500	ns
t <sub>r</sub>	Rise time	$V_{gen} = 10 \text{ V R}_{gen} = 1000 \Omega$		0.4	1.1	μs
t <sub>d</sub> (off)	Turn-off delay time	(see Figure 26)		2.5	7	μs
t <sub>f</sub>	Fall time			1	4	μs
(di/dt)on	Turn-on current slope	$V_{DD} = 15 \text{ V I}_{D} = 3.5 \text{ A}$ $V_{in} = 10 \text{ V R}_{gen} = 10 \Omega$		50		A/µs
Qi	Total input charge	$V_{DD}$ = 12 V I <sub>D</sub> = 3.5 A V <sub>in</sub> = 10 V		18		nC

Table 8. Electrical characteristics: source drain diode
---

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>SD</sub> <sup>(1)</sup>	Forward on voltage	I <sub>SD</sub> = 3.5 A V <sub>in</sub> = 0			1.7	V
	Reverse recovery time	I <sub>SD</sub> = 3.5 A di/dt = 100 A/μs		40		ns
Q <sub>rr</sub> <sup>(2)</sup>	Reverse recovery charge	V <sub>DD</sub> = 30 V T <sub>j</sub> = 25 ℃		0.2		μC
I <sub>RRM</sub> <sup>(2)</sup>	Reverse recovery current	(see test circuit, Figure 28)		3.6		А

1. Pulsed: Pulse duration = 300  $\mu$ s, duty cycle 1.5 %

2. Parameters guaranteed by design/characterization



Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
l.,	Drain current limit	V <sub>in</sub> = 10 V V <sub>DS</sub> = 13 V	4	7	11	Α
l <sub>lim</sub>		$V_{in} = 5 V V_{DS} = 13 V$	4	7	11	Α
t <sub>dlim</sub> <sup>(1)</sup>	Step response	V <sub>in</sub> = 10 V		13	20	μs
<sup>L</sup> dlim `´	Current limit	$V_{in} = 5 V$		15	25	μs
T <sub>jsh</sub> <sup>(1)</sup>	Overtemperature shutdown		150			C
T <sub>jrs</sub> <sup>(1)</sup>	Overtemperature reset		135			°C
l <sub>gf</sub> <sup>(1)</sup>	Fault sink current	$V_{in} = 10 V V_{DS} = 13 V$ $V_{in} = 5 V V_{DS} = 13 V$		50		mA
'gf`´	Fault Sink Cullent	$V_{in} = 5 V V_{DS} = 13 V$		20		mA
$E_{as}^{(1)}$	Single pulse avalanche energy	starting T <sub>j</sub> = 25°C V <sub>DD</sub> = 20 V V <sub>in</sub> = 10 V R <sub>gen</sub> = 1 K $\Omega$ L = 30 mH	0.4			J

 Table 9.
 Electrical characteristics: protection

1. Pulsed: Pulse duration = 300  $\mu$ s, duty cycle 1.5 %



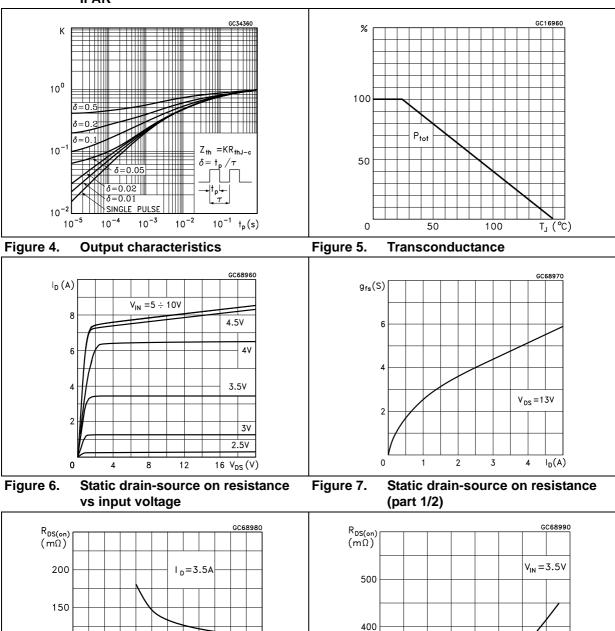
### 3 **Protection features**

During normal operation, the Input pin is electrically connected to the gate of the internal power MOSFET. The device then behaves like a standard power MOSFET and can be used as a switch from DC to 50 KHz. The only difference from the user's standpoint is that a small DC current (liss) flows into the Input pin in order to supply the internal circuitry.

The device integrates:

- Overvoltage clamp protection: internally set at 42 V, along with the rugged avalanche characteristics of the Power MOSFET stage give this device unrivalled ruggedness and energy handling capability. This feature is mainly important when driving inductive loads.
- Linear current limiter circuit: limits the drain current ld to llim whatever the Input pin voltage. When the current limiter is active, the device operates in the linear region, so power dissipation may exceed the capability of the heatsink. Both case and junction temperatures increase, and if this phase lasts long enough, junction temperature may reach the overtemperature threshold T<sub>jsh</sub>.
- Overtemperature and short circuit protection: these are based on sensing the chip temperature and are not dependent on the input voltage. The location of the sensing element on the chip in the power stage area ensures fast, accurate detection of the junction temperature. Overtemperature cutout occurs at minimum 150 °C. The device is automatically restarted when the chip temperature falls below 135 °C.
- Status feedback: in the case of an overtemperature fault condition, a Status Feedback is provided through the Input pin. The internal protection circuit disconnects the input from the gate and connects it instead to ground via an equivalent resistance of 100 Ω. The failure can be detected by monitoring the voltage at the Input pin, which will be close to ground potential.

Additional features of this device are ESD protection according to the Human Body model and the ability to be driven from a TTL Logic circuit (with a small increase in RDS(on)).



300

200 L 0

0.4

0.8

 $I_{D}(A)$ 

57

1.2

Figure 2. Thermal impedance for DPAK / IPAK

Figure 3. Derating curve

100

50

0

2.5

5

10

7.5

12.5 VIN(V)

R<sub>DS(on)</sub> (mΩ)

180

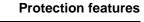
160

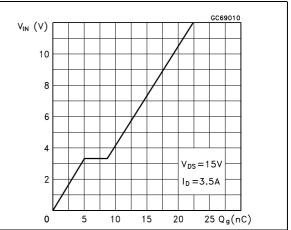
140

120

100

0





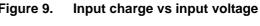


GC69000

 $I_{D}(A)$ 

4

 $V_{IN} = 5V$ 



1 Figure 10. Capacitance variations

 $V_{IN} = 10V$ 

2

3

Figure 11. Normalized input threshold voltage vs temperature

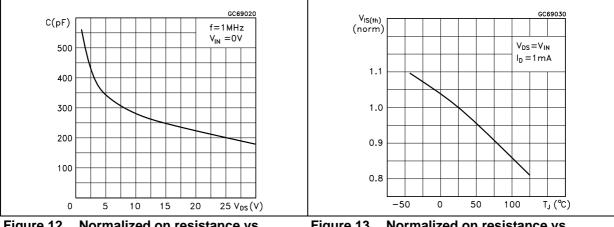
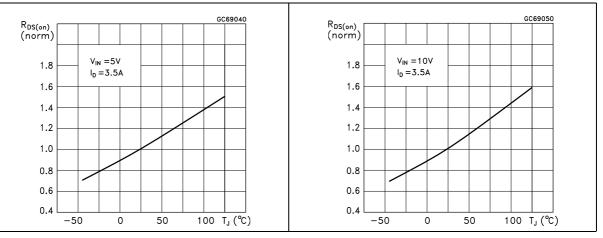


Figure 12. Normalized on resistance vs temperature (part 1/2)

Figure 13. Normalized on resistance vs temperature (part 2/2)



57

Figure 14. Turn-on current slope(part 1/2)

Figure 15. Turn-on current slope(part 2/2)

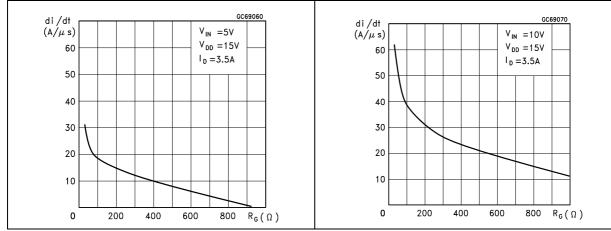


Figure 16. Turn-off drain-source voltage slope Figure 17. Turn-off drain-source voltage slope (part 1/2) (part 2/2)

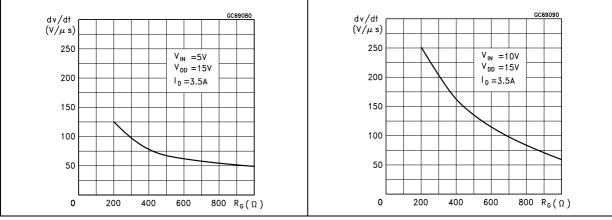
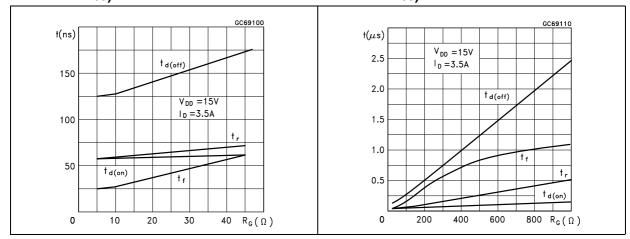


Figure 18. Switching time resistive load (part Figure 19. Switching time resistive load (part 1/3) 2/3)



GC69120 GC69130  $I_{lim}(A)$ t(ns)  $V_{DD} = 15V$ 7.6  $I_D = 3.5A$  $R_g = 4.7\Omega$ 175 tr 150  $V_{IN} = 10V$ 7.4 V<sub>DD</sub>=13V 125 t d(off) 100 7.2 75 t f 50 7.0 25 t<sub>d(on)</sub> 0 6.8 9  $V_{IN}(V)$ -50 0 50 100 T<sub>J</sub> (℃) 4 5 6 7 8 3

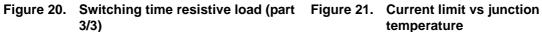


Figure 22. Step response current limit

Figure 23. Source drain diode forward characteristics

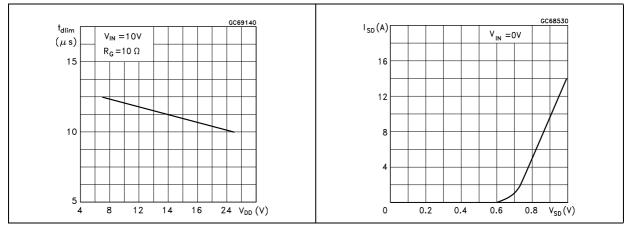
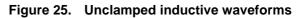


Figure 24. Unclamped inductive load test circuits



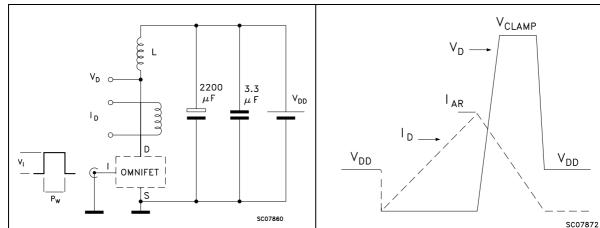
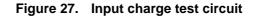
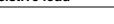
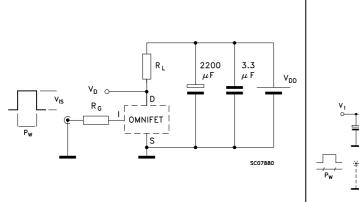


Figure 26. Switching times test circuits for resistive load







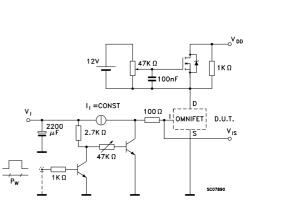
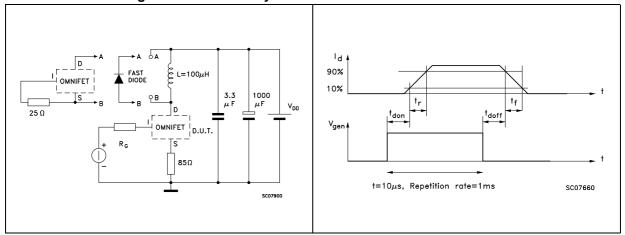


Figure 28. Test circuit for inductive load Figure 29. Waveforms switching and diode recovery times





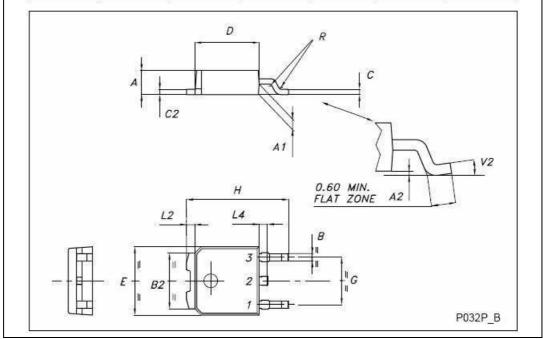
## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <u>www.st.com</u>.

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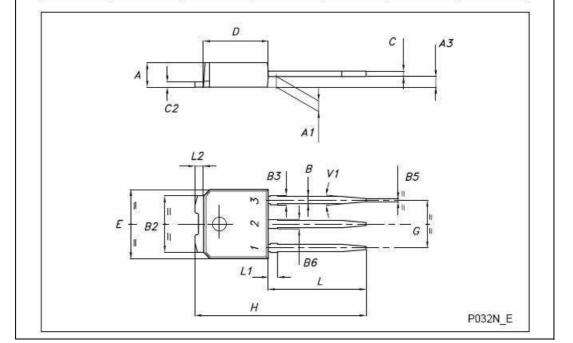
DIM.	mm		inch			
Dim.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	2.20		2.40	0.087		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03	2	0.23	0.001		0.009
В	0.64		0.90	0.025	2	0.035
B2	5.20		5.40	0.204		0.213
С	0.45	8	0.60	0.018		0.024
C2	0.48		0.60	0.019		0.024
D	6.00	X	6.20	0.236		0.244
E	6.40		6.60	0.252		0.260
G	4.40	с. 6	4.60	0.173		0.181
Н	9.35		10.10	0.368		0.398
L2		0.8			0.031	
L4	0.60		1.00	0.024		0.039
V2	0°	8	8°	0°		0°

Figure 30. TO-252 (DPAK) mechanical data



DIM.		mm		inch		
Dilw.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX
A	2.20		2.40	0.087		0.094
A1	0.90		1.10	0.035		0.043
A3	0.70	÷	1.30	0.028		0.051
В	0.64	9 25	0.90	0.025		0.035
B2	5.20	6	5.40	0.204		0.213
B3		_	0.85			0.033
B5		0.30	86 8.2		0.012	
B6	2 2		0.95	l		0.037
С	0.45		0.60	0.018		0.024
C2	0.48	2	0.60	0.019		0.024
D	6.00	5	6.20	0.237		0.244
Е	6.40		6.60	0.252		0.260
G	4.40	2	4.60	0.173		0.181
Н	15.90		16.30	0.626		0.642
L	9.00		9.40	0.354		0.370
L1	0.80	2	1.20	0.031		0.047
L2	de a	0.80	1.00	0	0.031	0.039
V1		10°			10°	

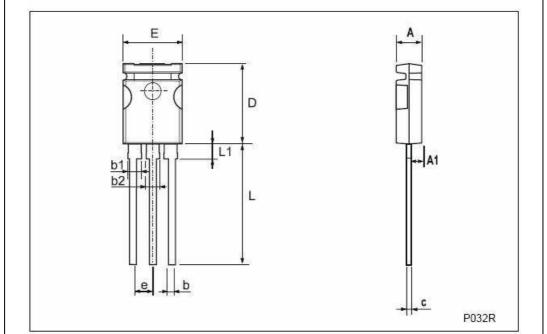
Figure 31. TO-251 (IPAK) mechanical data



57

DIM.		mm		inch		
570010 (790010)	MIN.	TYP.	MAX.	MIN.	TYP.	MAX
A	2.85		3.05	1.122		1.200
A1	1.47		1.67	0.578		0.657
b	0.40		0.60	0.157		0.236
b1	1.4		1.6	0.551		0.630
b2	1.3		1.5	0.511		0.590
C	0.45	-	0.6	0.177		0.236
D	10.5	8	10.9	4.133		4.291
е	2.2	-	2.8	0.866		1.102
Е	7.45	8. 10	7.75	2.933		3.051
L	15.5		15.9	6.102		6.260
L1	1.95	2	2.35	0.767		0.925

### Figure 32. SOT-82FM mechanical data



# 5 Revision history

Table 10. Document	revision	history	
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Date	Revision	Changes
21-Jun-2004	0.1	Initial release.
18-Mar-2009	1	Document reformatted. Added Table 1: Device summary on page 1. Updated Section 4: Package information on page 13



# 5 Revision history

Table 10	Document	revision	history
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Date	Revision	Changes
21-Jun-2004	1	Initial release.
25-Sep-2013 2		Updated Disclaimer



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